Product / Process Change Notice

PCN No.: <u>Q000-PCN-PA201502-02</u>

Date: 2015-02-17

Change Title: JCET site change from C3 factory to C8 factory.

Change Classification: 🗹 Major 🗖 Minor

Change item: □ Design □ Raw Material □ Wafer FAB ☑ Package Assembly □ Testing □ Others:

Affected Product(s) :

The affected part no. list, please refer to the Table I for more information.

Description of Change(s) :

JCET's production line for SOP 8L and MSOP 8L package types will be moved from C3 factory(No. 275 Binjiang Rd, Jiangyin, Jiangsu, China) to C8 factory(No.5 Putuoshan Road, Susu Industrial Park, Suqian, Jiangsu, China). Nuvoton had done the qualification for C8 factory, the related qualification report was showed as appendix A.

Reason for Change(s) :

In order to have product structure optimization, Nuvoton's subcontractor JCET changed the production line for for SOP 8L and MSOP 8L package types from C3 factory to C8 factory.

Impact of Change(s) : (positive & negative)

Form: No change.

Fit: No change.

Function: No concern.

Reliability: No concern(Passed Nuvoton package qualification.)

Qualification Plan/ Results :

The qualification had been done as per Nuvoton's standard qualification procedures, please refer to appendix A for the qualification report.

Implementation Plan :

□ Date Code: onward □ Lot No.:	onward Implemented date: <u>May 17, 2015(scheduled)</u>
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Originator:	HYLai / Q100	Approval:(QRA Director)	C.C. Chen/ Q000		
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Contact for Questions & Concerns					
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Customer Comments: Note: Please sign this

□ Approval	□ Disapproval	Con	ditional Appr	oval:				<u>.</u>	
Date:	Dept. nan	ne:			Person ir	h charge:			<u> </u>
<i>Follow-up and Trac</i> A. copies to	cing:								
FAB : 🗆 Integra	tion								
Test / Product:	oc]		0					
Design/ Marketi	ing: □	□					•		
Production cont	trol/ Others: 🗆			П			Г]	

B. Changes:

1. Document / Test program:

Document No/ test	Document name/ test program name	version		responsibor	Completed date	Remark
program		before	after		L	

Verifed by: _____.

Table I: Affected part lists

Part No.	Part No.	Part No.	Part No.	Part No.
W83773G	W83772G	NCT3943S	NCT3941S	W83310G-R
W83L771ASG	NCT3012S	NCT3720S	NCT3941S-A	W83310G-R2
W83L771AWG	NCT3012S-A	NCT3101S	NCT3942S	W83312SN
W83L771AWG-2	W83321G	NCT3730S	NCT3945S	NCT3720S-L
NCT5927W	NCT3946S	NCT3730S-L	W83310DG	NCT3101S
NCT7368S	W83323G	NCT3940S	W83310DG-A	NCT3942S
NCT7718W	NCT3230S	NCT3940S-A		



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Appendix A: The qualification report for C8 factory

PACKAGE QUALIFICATION REPORT

Company : JIANGSU Changjiang Electronics . Package : SOP 8L / MSOP 8L Package Package Material : Green Wire Bonding Material : Cu wire

RA ENGINEER : 黄 玠 升

CSHuang

RA MANAGER

SUMMARY

The SOP8L and MSOP 8L packages product was passed the qualification tests. A summary of the test result was as follows:

₽. Pre-condition Test	: 0/600
ि. Pressure Cooker Test	: 0/135
ि. Temperature Cycle Test	: 0/135
ि. Highly Temp. Storage Life Test	: 0/135

Results of the life tests and environmental tests as well as the methods used on SOP 8L and MSOP 8L packages are described in details in the report.



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I. ENVIRONMENTAL TEST

A. Introduction

- 1. Pre-condition Test
- 2. Pressure Cooker Test (PCT)
- 3. Temperature Cycle Test (TCT)
- 4. High Temp. Storage Life Test(HTSL)

B. Test Results

- 1. Pre-condition Test
- 2. Pressure Cooker Test (PCT)
- 3. Temperature Cycle Test (TCT)
- 4. Highly Temp. Storage Life Test(HTSL)

II. ENVIRONMENTAL TESTS OF PROCEDURE

A. Introduction

1. Pre-condition Test

1.1 SCOPE

Pre-condition Test is to measure the resistance of SMD (Surface Mount Devices) to the storage environment at the customer site and to thermal stress created by IR reflow or Vapor Phase Reflow.

1.2 TEST CONDITION

Step 1 : TCT(-65°C/150°C, 5 cycles)

Publication Release Date: Feb. 2015

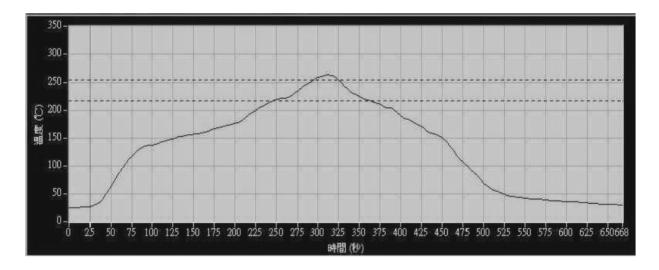
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Step 2 : Bake(125°C, 24 hours) Step 3 : Soak(30°C/60%RH, 192 hours) Step 4 : IR reflow (260 °C), 3 Passes.

1.3 SAT COFIRMATION: To confirm delamination, cracking, popcorn . Criteria: IPC/JEDEC J-STD-020C





Temp.	Criteria
Preheat 150 °C to 200 °C	60~180 sec
Time maintained above: Above 217 ℃	60~150 sec
Peak temp	260 ℃ +0 ℃/-5 ℃
Time within 5 ℃ of actual Peak Temperature of peak	20~40 sec

2. Pressure Cooker Test (PCT)

2.1 SCOPE

PCT is to evaluate the device resistance to moisture penetration.

2.2 TEST CONDITION

Ta = 121°C, RH = 100%, Td = 168 Hrs. 2 ATM ,(JESD22-A102-A)

3. Temperature Cycle Test (TCT)

3.1 SCOPE

TCT is to evaluate the resistance of device to environmental temperature change.

3.2 TEST CONDITION

-65°C / 15min, transfer time 1min, +150 °C/15min, 1000 cycles. MIL-STD-883E, Method 1010, Condition "C".

MIL-STD-883E, Method 1010, Condition C.

4. Highly Temp. Storage Life Test (HTSL)

4.1 SCOPE

The purpose of this test is to determine the effect on solid state electronic devices of storage at elevated temperature without electrical stress applied.

4.2 Test condition:

Temperature: 150°C, Time: 500/1000hrs

B. Test Results

1. Pre-condition Test

1.1 Pre-condition Test Result

Run	Lot No	SAT before Precondition		SAT After Precondition		Electric result
		Topside Backside		Topside	Backside	
#1	E433B003-01	0/200	0/200	0/200	0/200	0/200
#2	E433B003-02	0/200	0/200	0/200	0/200	0/200
#3	E433B003-03	0/200	0/200	0/200	0/200	0/200

*Criteria: Acc/Rej = 0/1.



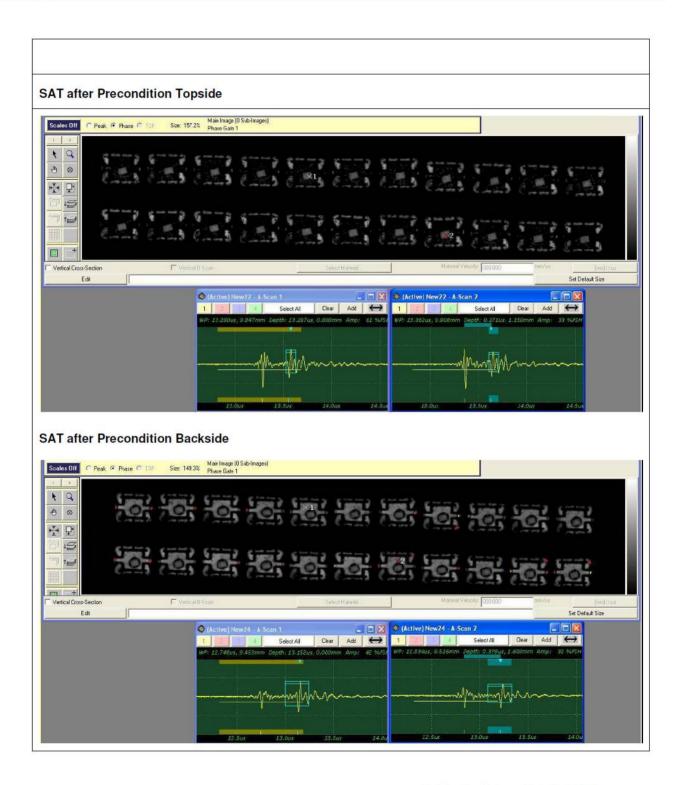
1.2 SAT confirmation

	Phase C TOF Size: 164.2% Ph	ain Image (D Sub-Images) aase Glade 1	
	8282		
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2. Pressure Cooker Test (PCT)

Run	Lot No	168 Hrs	Remark
#1	E433B003-01	0/45	
#2	E433B003-02	0/45	
#3	E433B003-03	0/45	

*Criteria : Acc/Rej = 0/1.

3. Temperature Cycle Test (TCT)

Run	Lot No	500 Cycles	Remark
#1	E433B003-01	0/45	
#2	E433B003-02	0/45	
#3	E433B003-03	0/45	

*Criteria : Acc/Rej = 0/1.

Run	Lot No	1000 Cycles	Remark
#1	E433B003-01	0/45	
#2	E433B003-02	0/45	
#3	E433B003-03	0/45	

*Criteria : Acc/Rej = 0/1.

4. Highly Temp. Storage Life Test (HTSL)

Run	Lot No	500 Hrs	Remark
#1	E433B003-01	0/45	
#2	E433B003-02	0/45	
#3	E433B003-03	0/45	

*Criteria : Acc/Rej = 0/1.

Run	Lot No	1000 Hrs	Remark
#1	E433B003-01	0/45	
#2	E433B003-02	0/45	
#3	E433B003-03	0/45	

*Criteria : Acc/Rej = 0/1.

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